

IBM-POU920020057US1 Examiner D.D.Nguyen,
10/755922 - 2 -

IBM

C: Amendments to The Claims:

What is claimed is:

- 1 1. (Original in Divisional Application) Land Grid Array
- 2 structure comprising,
- 3 a flex film interposer for providing a Land Grid Array (LGA)
- 4 electrical connection disposed between a Multi-Chip Module
- 5 (MCM) and the next level of integration ~~such~~ of a Land Grid
- 6 Array system and said flex film, wherein said interposer
- 7 also provides means integral to said flex film interposer
- 8 for implementing a desired Engineering Change (EC) and said
- 9 flex film interposer also integrally provides means for
- decoupling power to ground in the Land Grid Array structure
- to minimize switching activity effects on the Land Grid
- Array system when mounted on a system board.
2. (Cancelled)
3. (Cancelled)
4. (New) A Land Grid Array structure according to claim 1
- wherein said flex film interposer has a plated through hole
- formed therethrough and there is a fuzz button rivit
- expansion pin inserted in said hole to insulate the plated
- through hole from the system board.